



2026 NYCU Inbound Internship Program



Taiwan

Taiwan is a compact island brimming with cutting-edge technology, vibrant culture, and welcoming people. Explore Taiwan up close through paid internships at companies, research institutions, or laboratories affiliated with National Yang Ming Chiao Tung University (NYCU).

NYCU is partnering with industry leaders such as TSMC, E.SUN Bank, UMC, Micron, and HHRI to provide over 20 internship opportunities to international students from selected partner universities annually.

INTRODUCTION OF NYCU

History



- Founded originally as Nanyang College in Shanghai in 1896.
- Re-established as NCTU in 1958 in Hsinchu, Taiwan.
- Merged with National Yang Ming University in 2021 and became National Yang Ming Chiao Tung University (NYCU)

Guangfu Campus



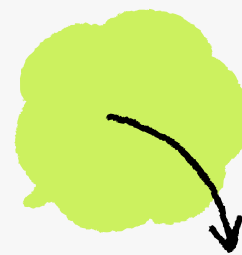
- Located in Hsinchu, Taiwan's "Silicon Valley"
- Adjacent to the Hsinchu Science Park, home to many leading tech companies
- Close to 7 national laboratories, 2 of which are located on campus
- Just a 5-minute drive to the Industrial Technology Research Institute (ITRI)
- Other campuses include Yangming, Boai, Liujia, Gueiren, and Beimen

Students



- A research-oriented university with 8,600+ undergraduates and 12,300+ graduate students
- International students from over 60 countries
- Member of the University System of Taiwan
(UST: National Central University, National Tsing Hua University, and National Chengchi University)

THE MERGER OF NCTU & NYMU



National Yang Ming University (hereinafter referred to as Yang Ming) and National Chiao Tung University (hereinafter referred to as Chiao Tung) formally merged into the "National Yang Ming Chiao Tung University" (NYCU) on February 1, 2021. Yang Ming, which focuses on biomedical research, and Chiao Tung, which focuses on electronic communication research, are both top-tier universities in Taiwan. Under the principle of "reciprocity and mutual trust", they have adopted a step-by-step

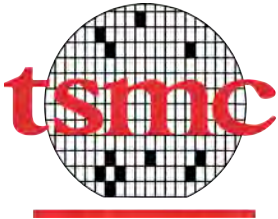


integration model to complement their expertise to bring forth a novel disciplinary domain of teaching and pioneer the future of research and innovation. Thus, it is imagined that the merger will eventually bring forth a great and innovative university that is second to none, with 1,400 teachers and 20,000 students collaborating to create a great generation that will develop and further Taiwan's emerging smart medical industry.



CORPORATE PARTNERS

01.



TSMC created the semiconductor Dedicated IC Foundry business model when it was founded in 1987. TSMC served about 535 customers and manufactured more than 12,302 products for various applications covering a variety of end markets, including smartphones, high-performance computing, the Internet of Things (IoT), automotive, and digital consumer electronics.

Annual capacity of the manufacturing facilities managed by TSMC and its subsidiaries exceeded 13 million 12-inch equivalent wafers in 2021. These facilities include four 12-inch wafer GIGAFAB® fabs, four 8-inch wafer fabs, and one 6-inch wafer fab – all in Taiwan – as well as one 12-inch wafer fab at a wholly owned subsidiary, TSMC Nanjing Company Limited, and two 8-inch wafer fabs at wholly owned subsidiaries, WaferTech in the United States and TSMC China Company Limited.

In December 2021, TSMC established a subsidiary, Japan Advanced Semiconductor Manufacturing, Inc. (JASM), in Kumamoto, Japan. JASM will construct and operate a 12-inch wafer, with production targeted to begin by the end of 2024. Meanwhile, the Company continued to execute its plan for an advanced semiconductor fab in Arizona, the United States, with production targeted for 2024.

TSMC Summer Intern Program provides an unique experience for students to learn about the semiconductor industry and have a first-hand experience of career life in TSMC. You will not only join a series of training sessions related to your major, but also be part of the team and expected to provide solutions and create valuable impacts to our company.

For Engineering field related positions, we welcome all the talents from STEM fields (Electronics, Electrical Engineering, Physics, Material Science and Engineering, Chemistry, Chemical Engineering, Mechanical and Automation Engineering, Computer Science, Industrial Engineering) to join us!





E.SUN Bank was established in 1992 by a group of professionals and aims to build the best bank in Taiwan. Keeping our promise to provide comprehensive banking services to customers and enhance brand image, E.SUN FHC was then established in 2002 with the core strategy of establishing strong roots in Taiwan and making a footprint in Asia over

the coming decade. To accommodate the trend of new technology, E.SUN is dedicated to providing customers the best user experience by offering a customized, online-to-offline and cross-border digital banking service.

Intelligent Banking Division (IBD) at E.SUN Bank is devoted to innovating and enhancing financial services from all sorts of aspects based on data analytics and AI. IBD specializes in using cutting-edge data analysis and machine learning techniques with the rich data assets to maximize the customer and corporate values simultaneously. The main role and responsibility of IBD includes: discovering new AI applications and applying them to improve the breadth, depth, and quality of financial services, introducing data techniques and AI, and deepening their use to further business growth, and advocating the data culture inside the corporation as the Center of Excellence for data analytics and AI.



UMC is a leading global semiconductor foundry company. The company provides high-quality IC fabrication services, focusing on logic and various specialty technologies to serve all major sectors of the electronics industry. UMC's comprehensive IC processing technologies and manufacturing solutions include Logic/Mixed-Signal, embedded High-Voltage,

embedded Non-Volatile Memory, RFSOI, BCD, etc. Most of UMC's 12-in & 8-in fabs with its core R&D are located in Taiwan, with additional ones throughout Asia.

UMC has a total of 12 fabs in production with a combined capacity of more than 400,000 wafers per month (12-in equivalent), and all of them are certified with the IATF 16949 automotive quality standard. UMC is headquartered in Hsinchu, Taiwan, with local offices in the United States, Europe, China, Japan, Korea, and Singapore, with a worldwide total of 20,000 employees.



The world is moving to a new economic model, where data is driving value creation in ways we had not imagined just a few years ago. Data is today's new business currency, and memory and storage are emerging as strategic differentiators that will redefine how we extract value

from data to learn, explore, communicate, and experience. As the leader in innovative memory solutions, Micron is helping the world make sense of data by delivering technology that is transforming how the world uses information to enrich life for all. Through our global brands

— Micron and Crucial — we offer the industry's broadest portfolio. We are the only company manufacturing today's major memory and storage technologies: DRAM, NAND, NOR, and 3D XPoint™ memory. Our solutions are purpose-built to leverage the value of data to unlock financial insights, accelerate scientific breakthroughs, and enhance communication around the world.

From our roots in Boise, Idaho, Micron has grown into an influential global presence committed to being the best memory company in the world. This means conducting business with integrity, accountability, and professionalism, and supporting our global community.



Established in Taiwan in 1974, Hon Hai Technology Group (Foxconn) (TWSE: 2317) is the world's largest electronics manufacturer. Foxconn is also the leading technological solution provider, and it continuously leverages its expertise in software and hardware to integrate its unique manufacturing systems with emerging technol-

ogies. The Group has expanded not only its capabilities into the development of electric vehicles, digital health, and robotics, but also three key technologies – AI, semiconductors, and new-generation communications technology – which are key to driving its long-term growth strategy and the four core product pillars: Smart Consumer Electronics, Cloud and Networking, Computing Products and Components, and Others.

The Hon Hai Research Institute (HHRI) represents a key step in Foxconn Group's development strategy towards our F3.0 transformation to the new industries goal. HHRI focuses on prospective technologies over the next 3–7 years, thereby strengthening the Group's technological and product innovations, supporting enhancements in core competitiveness.

Foxconn "3+3" strategy

- 3 key industries: electric vehicles, digital health, and robotics.
- 3 key technologies: AI, semiconductors, and next-generation communications.

Company	NYCU	Micron	TSMC	UMC	E.SUN Bank	HHRI
NYCU Stipend (for 2 months)	Up to NTD 55,000	N/A				
Monthly Salary	X	Negotiable	Negotiable	Bachelor: 38,000 NTD Master/PhD: 45,000 - 55,000 NTD	30,000 NTD (Negotiable)	Negotiable
Economy Class Return Flights	X	Depends on the hiring division	Depends on the hiring division	Not provided	Depends on the hiring division	Depends on the hiring division
Housing	Fee-paying on-campus	Qualified applicants may apply for dormitory in Taichung or housing subsidy in Taoyuan	Depends on the hiring division.	Depends on the hiring division	Qualified applicants may apply for dormitory in Taipei	Depends on the hiring division
Required Mandarin Proficiency	N/A	N/A	Depends on the hiring division; oral communication ability is a plus	Proficiency in Mandarin is a plus	Fair; oral communication ability is a plus	N/A
Level of Study Accepted	Bachelor (Senior) Master PhD	Bachelor (Senior) Master PhD	Bachelor (Junior) Master (Preferred) PhD (Preferred)	Master PhD	Bachelor, Master	Bachelor Master PhD
Internship Duration	June-August	June-August	June-August	2026/06/22-08/31	2026/07/01-08/31	June-August

ABOUT INTERNSHIP PROGRAM



PROGRAM HIGHLIGHTS

- Visit to NYCU [laboratories and campus tour](#)
- [8 weeks of internships](#) or as stipulated by the host
- Choose from [internships in the industry or at NYCU](#)
- Opening and closing events with [cultural tours](#).

INTERNSHIP TYPES & OPPORTUNITIES

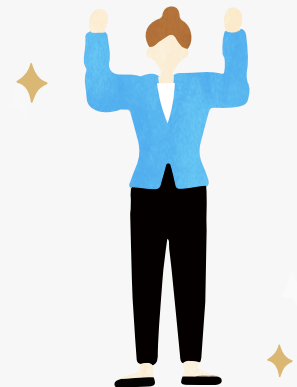
1. INTERNSHIP IN THE INDUSTRY

For the list of internship openings, please see [here](#).

2. RESEARCH AT NYCU

For the list of possible host supervisors, please see [here](#).

In addition to the supervisors listed, you can also contact other NYCU professors for opportunities for short-term research guidance.



ELIGIBILITY

Open to undergraduates, graduating seniors, and graduate students in all disciplines from selected institutions

(subject to internship openings offered by companies and NYCU host supervisors.)



REQUIREMENTS

Each internship position has its own set of requirements.



BENEFITS

- Some companies provide **free housing** and / or **reimburse round-trip economy class flights**
- NYCU **student buddy**
- **Monthly salary & stipend**

APPLICATION

APPLICATION DEADLINE

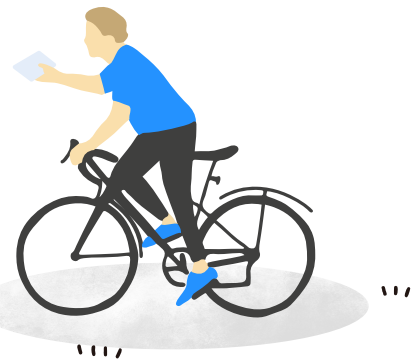
DECEMBER 31ST, 2025

for a summer internship in the industry

MARCH 15TH, 2026

for a research internship at NYCU

(Application accepted thereafter, depending on available placements)



PLACEMENT PROCESS

1. Students submit applications and required documents online.
2. Companies or supervisors at NYCU conduct online interviews with applicants.
3. Placement is finalized around mid-April to May.



HOW TO APPLY



✓ Online Application link (company internships)

click here! →

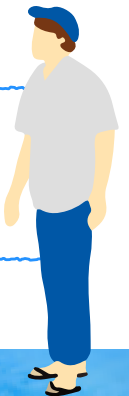


✓ NYCU internships are arranged by contacting professors directly.
Please visit our official webpage for complete details and further information

click here! →

✓ TSMC requires all applicants to create an account and upload a CV simultaneously with submitting an application to NYCU. Refer to the link

click here! →



CHECK

- ✓ Curriculum Vitae (CV) in **English**
- ✓ Latest certificate of enrollment
- ✓ **Copy of a valid passport** valid for at least 6 months upon arrival in Taiwan
- ✓ Transcript of Records
- ✓ Cover letter
- ✓ **Research proposal** No more than one A4-sized page; for applicants of lab research only.

Acceptance letters will be sent to students to initiate the visa application process.





CONTACTS



Office of International Affairs, NYCU



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Instagram



NYUC

 click icon!

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